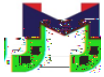




	Value	Unit
	60	V
	1.6	V
	34	A
	11.3	mΩ
	14.6	



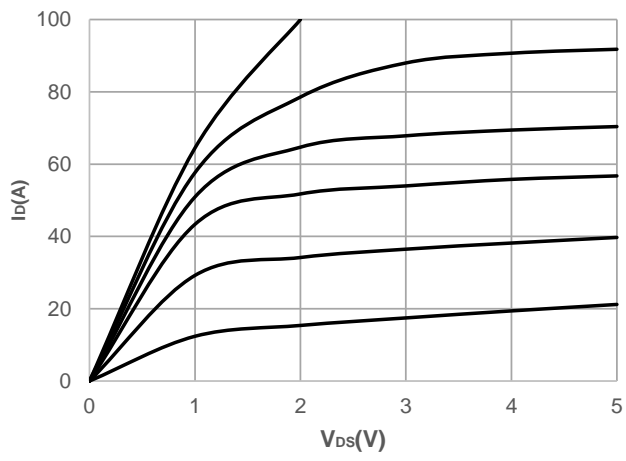
**Electrical Characteristics** ($T_J = 25^\circ\text{C}$ unless otherwise specified)

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
Off Characteristics						
$V_{(BR)DSS}$	Drain-Source Breakdown Voltage	$I_D = 250\mu\text{A}$, $V_{GS} = 0\text{V}$	60	-	-	V
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS} = 48\text{V}$, $V_{GS} = 0\text{V}$	-	-	1.0	μ
I_{GSS}	Gate-Body Leakage Current	$V_{DS} = 0\text{V}$, $V_{GS} = \pm 20\text{V}$	-	-	± 100	
On Characteristics						
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS} = V_{GS}$, $I_D = 250\mu\text{A}$	1.2	1.6	2.1	V
$R_{DS(ON)}$	Static Drain-Source ON-Resistance ⁽⁴⁾	$V_{GS} = 10\text{V}$, $I_D = 20\text{A}$	-	11.3	14.7	m Ω
		$V_{GS} = 4.5\text{V}$, $I_D = 15\text{A}$	-	14.6	19.0	m Ω
Dynamic Characteristics						
R_g	Gate Resistance	$f = 1\text{MHz}$	-	1.8	-	Ω
C_{iss}	Input Capacitance	$V_{GS} = 0\text{V}$, $V_{DS} = 30\text{V}$, $f = 1\text{MHz}$	542	758	1024	pF
C_{oss}	Output Capacitance		275	385	520	pF
C_{rss}	Reverse Transfer Capacitance		19	26	35	pF
Q_g	Total Gate Charge	$V_{GS} = 0$ to 10V $V_{DS} = 30\text{V}$, $I_D = 20\text{A}$	10	14	19	nC
Q_{gs}	Gate Source Charge		-	2.7	-	nC
Q_{gd}	Gate Drain("Miller") Charge		-	3.2	-	nC
Switching Characteristics						
$t_{d(on)}$	Turn-On DelayTime	$V_{GS} = 10\text{V}$, $V_{DD} = 30\text{V}$ $I_D = 20\text{A}$, $R_{GEN} = 3\Omega$	-	5.4	-	ns
t_r	Turn-On Rise Time		-	14	-	ns
$t_{d(off)}$	Turn-Off DelayTime		-	16	-	ns
t_f	Turn-Off Fall Time		-	4.3	-	ns
Body Diode Characteristics						
I_S	Maximum Continuous Body Diode Forward Current		-	-	34	A
I_{SM}	Maximum Pulsed Body Diode Forward Current		-	-	135	A
V_{SD}	Body Diode Forward Voltage	$V_{GS} = 0\text{V}$, $I_S = 20\text{A}$	-		1.2	V
t_{rr}	Body Diode Reverse Recovery Time	$I_F = 20\text{A}$, $di/dt = 100\text{A/us}$	16	22	30	ns
Q_{rr}	Body Diode Reverse Recovery Charge		-	11	-	nC

- Notes:
1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature.
 2. E_{AS} condition: Starting $T_J = 25^\circ\text{C}$, $V_{DD} = 30\text{V}$, $V_{GS} = 10\text{V}$, $R_G = 25\text{ohm}$, $L = 3\text{mH}$, $I_{AS} = 5.6\text{A}$, $V_{DD} = 0\text{V}$ during time in avalanche.
 3. $R_{DS(ON)}$ is measured with the device mounted on a 1inch^2 pad of 2oz copper FR4 PCB.
 4. Pulse Test: Pulse Width 0.5%.



Typical Performance Characteristics





Typical Performance Characteristics

Figure 11: Normalized Breakdown voltage vs. Junction Temperature

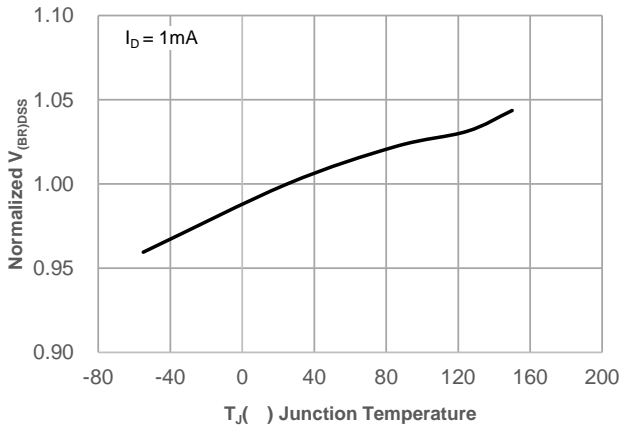


Figure 12: Normalized on Resistance vs. Junction Temperature

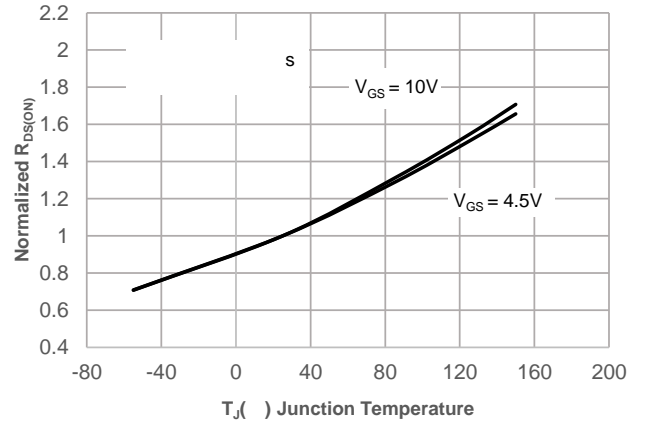


Figure 14: $R_{DS(ON)}$ vs. V_{GS}

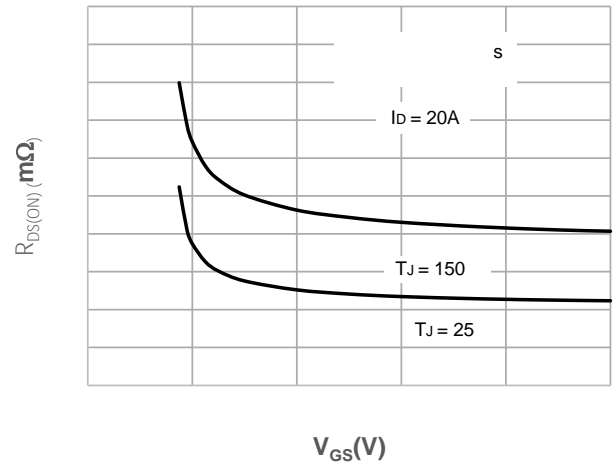
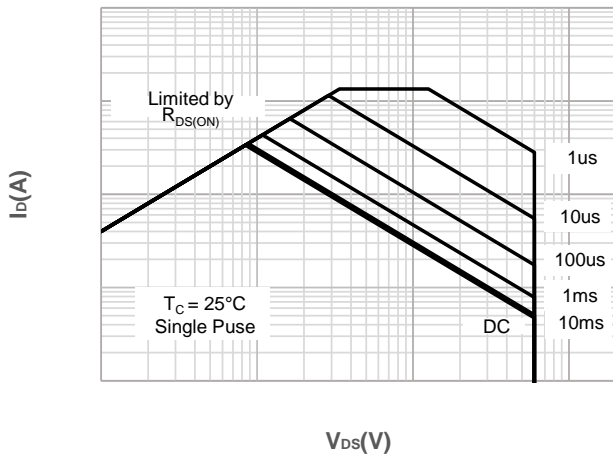


Figure 15: Maximum Safe Operating Area



Test Circuit



Figure 1: Gate Charge Test Circuit & Waveform

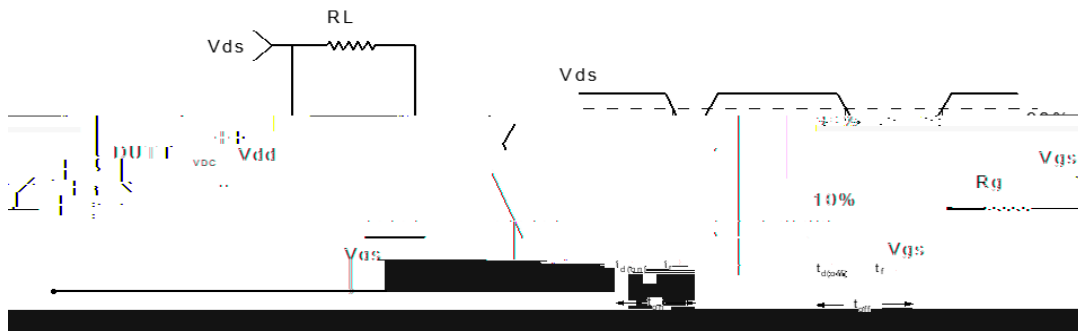


Figure 2: Resistive Switching Test Circuit & Waveform

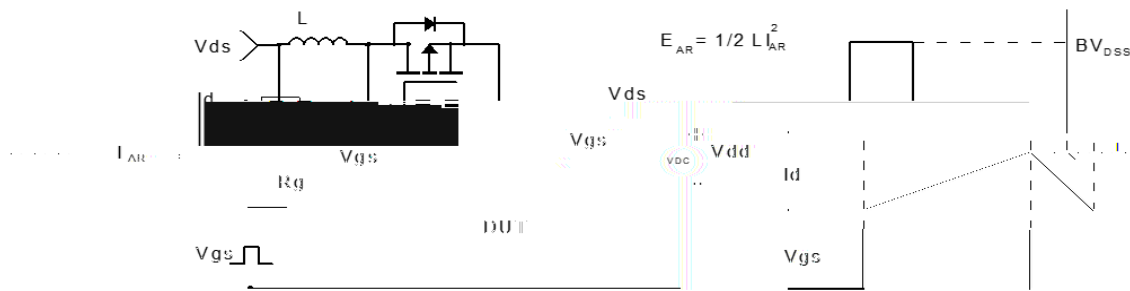


Figure 3: Unclamped Inductive Switching Test Circuit & Waveform

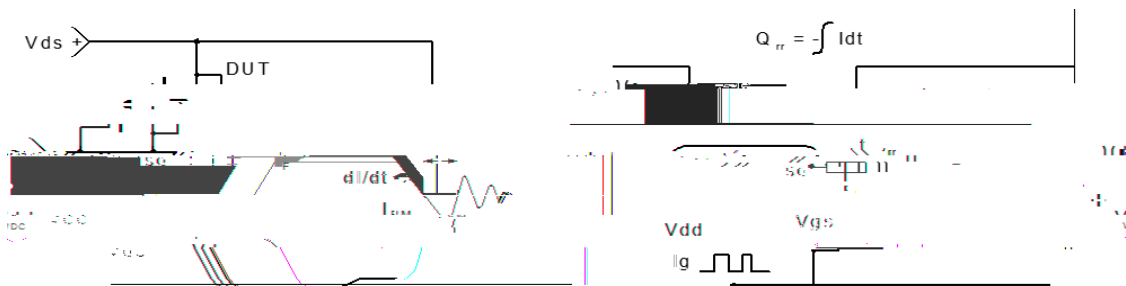


Figure 4: Diode Recovery Test Circuit & Waveform



Package Mechanical Data(PDFN3X3-8L-D)

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